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FOLEY & LARDNER LLP			DICKEY, THOMAS L	
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MADISON, W			2826	

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Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	TA II			
Office Action Summary		Application No.	Applicant(s)			
		10/772,573	MAWST ET AL.			
	Office Action Summary	Examiner	Art Unit			
	71 44411140 0477	Thomas L. Dickey	2826			
Period fo	The MAILING DATE of this communication apport Reply	pears on the cover sheet with the c	orrespondence address			
THE - Exte after - If the - If NC - Failt Any	ORTENED STATUTORY PERIOD FOR REPL' MAILING DATE OF THIS COMMUNICATION. nations of time may be available under the provisions of 37 CFR 1.1 SIX (6) MONTHS from the mailing date of this communication. e period for reply specified above is less than thirty (30) days, a repl period for reply is specified above, the maximum statutory period or to reply within the set or extended period for reply will, by statute reply received by the Office later than three months after the mailing ed patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be time y within the statutory minimum of thirty (30) days will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).			
Status						
1)⊠	Responsive to communication(s) filed on 12 Ju	ulv 2006.				
	•	action is non-final.				
3)	Since this application is in condition for allowa	nce except for formal matters, pro	secution as to the merits is			
	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposit	ion of Claims	,				
4)⊠	Claim(s) 1-67 is/are pending in the application		·			
	4a) Of the above claim(s) is/are withdrawn from consideration.					
	5) ☐ Claim(s) is/are allowed. 6) ☑ Claim(s) <u>1-21,23-26,28,29,32,34-46,48-52,55,56 and 64-67</u> is/are rejected.					
6)⊠						
7)⊠	☑ Claim(s) <u>22,27,30,31,33,47,53,54 and 57-63</u> is/are objected to.					
8)□	Claim(s) are subject to restriction and/o	r election requirement.				
Applicat	ion Papers					
9)[The specification is objected to by the Examine	er.				
	10)⊠ The drawing(s) filed on <u>05 February 2004</u> is/are: a)⊠ accepted or b)□ objected to by the Examiner.					
	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).					
	Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).					
11)	The oath or declaration is objected to by the Ex	caminer. Note the attached Office	Action or form PTO-152.			
Priority ι	under 35 U.S.C. § 119					
12)	Acknowledgment is made of a claim for foreign	priority under 35 U.S.C. § 119(a)	-(d) or (f).			
	☐ All b)☐ Some * c)☐ None of:	, , , , , , , , , , , , , , , , , , , ,	(-) (-).			
	1. Certified copies of the priority documents have been received.					
	2. Certified copies of the priority documents have been received in Application No					
	3. Copies of the certified copies of the priority documents have been received in this National Stage					
	application from the International Bureau	` ',	·			
* S	See the attached detailed Office action for a list	of the certified copies not receive	d.			
Attachmen 4\ ⊠ Nadia	• •	,, —				
	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948)	4) Interview Summary (Paper No(s)/Mail Da	(PTO-413) te.			
3) 🔲 Inforr	nation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date		atent Application (PTO-152)			
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DETAILED ACTION

1. The amendment filed on 12/19/05 has been entered.

Initially, it is noted that applicant added claims 66 and 67 without supplying reasons why said claims are patentable over the art of record, in violation of 37 CFR 1.111. However, no harm seems to have accrued. Applicants do argue the patentability of claims 1 and 39, from which the new claims depend. Further, it is clear that the new claims read on the same art as do claims 2 and 41, respectively.

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. J S Harris Jr, "GalnNAs long-wavelength lasers: progress and challenges," Semicond. Sci. Technol. 17 (2002) pp 1–12. In section 2 and figure 2 Harris Jr. supplies facts refuting Applicant's argument, found at pp. 12-13 and repeated page 16 of the paper filed 12/19/05, that one of skill in the art would lack the technical know-how to lattice match alloys of indium, gallium, arsenic, and nitrogen to an InP substrate, while adjusting the band gap of the resultant alloy. The examiner found Harris Jr on the Web after a two minute Google search. If Applicant had any technical skill in the art of III-V alloys (or were willing to spend a few minutes making herself aware of the state of said art), Applicant would understand how ludicrous her position is. For the last ten years, every writer in this field has either spent a few paragraphs explaining lattice

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matching, as Harris Jr. does, or simply assumed their reader knew all about it, as applicants do in their own specification. If there were any truth to Applicant's ludicrous suggestion – which there is not – her own claims would lack enablement.

New art has been applied to some of Applicant's claims. Consequently this action is Non-Final.

Double Patenting

2. The nonstatutory double patenting rejection is based on a judicially created doctrine grounded in public policy (a policy reflected in the statute) so as to prevent the unjustified or improper timewise extension of the "right to exclude" granted by a patent and to prevent possible harassment by multiple assignees. See *In re Goodman*, 11 F.3d 1046, 29 USPQ2d 2010 (Fed. Cir. 1993); *In re Longi*, 759 F.2d 887, 225 USPQ 645 (Fed. Cir. 1985); *In re Van Ornum*, 686 F.2d 937, 214 USPQ 761 (CCPA 1982); *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970); and, *In re Thorington*, 418 F.2d 528, 163 USPQ 644 (CCPA 1969).

A timely filed terminal disclaimer in compliance with 37 CFR 1.321(c) may be used to overcome an actual or provisional rejection based on a nonstatutory double patenting ground provided the conflicting application or patent is shown to be commonly owned with this application. See 37 CFR 1.130(b).

Effective January 1, 1994, a registered attorney or agent of record may sign a terminal disclaimer. A terminal disclaimer signed by the assignee must fully comply with 37 CFR 3.73(b).

Claims 1,2,8,11,12,15, 16,17,18-21,23,24,25,26, 29,32,34,38, 39,48,49, and 52 stand rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1-33 of U.S. Patent No. 6,791,104 in view of PETER ET AL. ("Light-emitting diodes and laser diodes based on a Ga_{1-x}ln_xAs/GaAs_{1-y}Sb_y" Applied Physics Letters, 04/05/99, Vol. 74 Issue 14, pp1951-1953).

With regard to claims 1,2,8,11,12,15,53, and 54, claims 1-33 of Patent No. 6,791,104 disclose an optoelectronic device comprising a multilayer semiconductor structure including a substrate and an active region, the active region comprising at least a hole quantum well layer of a semiconductor containing antimony and at least one electron quantum well layer adjacent to the hole quantum well layer which comprises a semiconductor containing nitrogen to provide a type II quantum well structure, wherein the semiconductor containing antimony is InGaAsSb and the semiconductor containing nitrogen is InAsN, wherein the semiconductor containing antimony is GaAsSb or InGaAsSb and the semiconductor containing nitrogen is InAsN or InGaAsN, wherein the electron quantum well layers and hole quantum well layer form a first quantum well stage, and wherein the active region comprises a plurality of

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quantum well stages adjacent to each other each having electron quantum well layers surrounding a hole quantum well layer, including means for providing optical feedback to form an edge-emitting laser or a vertical cavity surface-emitting laser.

Claims 1-33 do not disclose that the substrate is an InP substrate. However, Peter et al. discloses an optoelectronic device with an InP substrate. Note the first column of page 1951 of Peter et al. Peter et al. explain that the binary InP substrate is advantageous in that it is commercially used and thus technically advanced, has good thermal conductivity and low electrical resistance. Therefore, it would have been obvious to a person having skill in the art to replace the substrate of the device of claims 1-33 with the InP substrate such as taught by Peter et al. in order to provide a substrate that is technically advanced, has good thermal conductivity and low electrical resistance to thus provide higher reliability.

With regard to claims 16,17,18-21,23,24,25,26, and 59, claims 1-33 of Patent No. 6,791,104 disclose an optoelectronic device comprising a multilayer semiconductor structure including a substrate and an active region, the active region comprising at least a hole quantum well layer of GaAsSb or InGaAsSb and an electron quantum well layer of InAsN or InGaAsN on each side of the hole quantum well layer to provide a type II quantum well structure, wherein the electron quantum well layers are in compressive strain and the hole quantum well layer is in compressive strain and the thickness of

each electron quantum well layer and hole quantum well layer is between approximately 10 and 50 angstroms, wherein the electron quantum well layers and hole quantum well layer form a first quantum well stage, and wherein the active region comprises a plurality of quantum well stages adjacent to each other and the electron quantum well layer is an InAsN layer, wherein the hole quantum well layer is an InGaAsSb layer and the electron quantum well layer is an InAsN layer, and including means for providing optical feedback to form an edge-emitting laser or a vertical cavity surface-emitting laser.

Claims 1-33 do not disclose that the substrate is an InP substrate. However, Peter et al. discloses an optoelectronic device with an InP substrate. Note the first column of page 1951 of Peter et al. Peter et al. explain that the binary InP substrate is advantageous in that it is commercially used and thus technically advanced, has good thermal conductivity and low electrical resistance. Therefore, it would have been obvious to a person having skill in the art to replace the substrate of the device of claims 1-33 with the InP substrate such as taught by Peter et al. in order to provide a substrate that is technically advanced, has good thermal conductivity and low electrical resistance to thus provide higher reliability.

With regard to claims 27,29,32,34, and 38, claims 1-33 of Patent No. 6,791,104 disclose an optoelectronic device comprising a multilayer semiconductor structure

including a substrate and an active region, the active region comprising at least a hole quantum well layer of GaAsSb and an electron quantum well layer of InAsN on each side of the hole quantum well layer to provide a type II quantum well structure wherein the electron quantum well layers are in compressive strain and the hole quantum well layer is in compressive strain, wherein the thickness of each electron quantum well layer and hole quantum well layer is between approximately 10 and 50 angstroms, wherein the electron quantum well layers and hole quantum well layer form a first quantum well stage, and wherein the active region comprises a plurality of quantum well stages adjacent to each other, and including means for providing optical feedback to form an edge-emitting laser or a vertical cavity surface-emitting laser.

Claims 1-33 do not disclose that the substrate is an InP substrate. However, Peter et al. discloses an optoelectronic device with an InP substrate. Note the first column of page 1951 of Peter et al. Peter et al. explain that the binary InP substrate is advantageous in that it is commercially used and thus technically advanced, has good thermal conductivity and low electrical resistance. Therefore, it would have been obvious to a person having skill in the art to replace the substrate of the device of claims 1-33 with the InP substrate such as taught by Peter et al. in order to provide a substrate that is technically advanced, has good thermal conductivity and low electrical resistance to thus provide higher reliability.

With regard to claims 39,48,49,52,62 and 63, claims 1-33 of Patent No. 6,791,104 disclose an semiconductor laser comprising (a) a multilayer semiconductor structure including a substrate and an active region, the active region comprising at least a hole quantum well layer of a semiconductor containing antimony and at least one electron quantum well layer comprising a semiconductor containing nitrogen adjacent to the hole quantum well layer to provide a type II quantum well structure; and (b) means for providing optical feedback to provide lasing action in the active region, wherein the means for providing optical feedback forms an edge-emitting laser or a vertical cavity surface-emitting laser, wherein the semiconductor containing antimony is InGaAsSb the semiconductor containing nitrogen is InAsN.

Claims 1-33 do not disclose that the substrate is an InP substrate. However, Peter et al. discloses an optoelectronic device with an InP substrate. Note the first column of page 1951 of Peter et al. Peter et al. explain that the binary InP substrate is advantageous in that it is commercially used and thus technically advanced, has good thermal conductivity and low electrical resistance. Therefore, it would have been obvious to a person having skill in the art to replace the substrate of the device of claims 1-33 with the InP substrate such as taught by Peter et al. in order to provide a substrate that is technically advanced, has good thermal conductivity and low electrical resistance to thus provide higher reliability.

Claim Rejections - 35 USC § 103

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

A. Claims 1,2,5,8,11-16,18,21,24,25,26,28,29,32,34-41,43-46,48-51, 64, and 65 are rejected under 35 U.S.C. 103(a) as being unpatentable over PETER ET AL. ("Light-emitting diodes and laser diodes based on a Ga_{1-x}In_xAs/GaAs_{1-y}Sb_y" Applied Physics Letters, 04/05/99, Vol. 74 Issue 14, pp1951-1953), in view of Major et al. (5,689,123).

With regard to claims 1,2,8, 11-14, 54, and 66 Peter et al. disclose a multilayer semiconductor structure including an InP substrate and an active region, the active region comprising at least a hole quantum well layer of a semiconductor containing antimony and at least one electron quantum well layer adjacent to the hole quantum well layer which comprises a first semiconductor to provide a type II quantum well structure, wherein the first semiconductor comprises InAs, the semiconductor containing antimony is GaAsSb or InGaAsSb and the first semiconductor comprises InAs or InGaAs, the electron quantum well layers are in compressive strain and the hole quantum well layer are in tensile strain, the electron quantum well layers and hole

quantum well layer form a first quantum well stage, and wherein the active region comprises a plurality of quantum well stages adjacent to each other each having electron quantum well layers surrounding a hole quantum well layer, and the active region generates light including means for providing optical feedback to form an edge-emitting laser or a vertical cavity surface-emitting laser.

With further regard to claims 39,40,41,43-46,48-51, 63-65, and 67 Peter et al. disclose a semiconductor laser including (a) an InP substrate and an active region, the active region comprising at least a hole quantum well layer of a semiconductor containing antimony and at least one electron quantum well layer comprising a first semiconductor adjacent to the hole quantum well layer to provide a type II quantum well structure; wherein there is an electron quantum well layer on each side of the hole quantum well layer and there is a barrier layer adjacent to each electron quantum well layer on each side of the hole quantum well layer to provide a conduction band profile for the active region having a W-shaped configuration, the semiconductor containing antimony is GaAsSb or InGaAsSb and the first semiconductor comprises InAs or InGaAs, wherein the electron quantum well layers are in compressive strain and the hole quantum well layer is in tensile strain, the thickness of each electron quantum well layer and hole quantum well layer is between approximately 10 and 50 angstroms, the electron quantum well layers and hole quantum well layer form a first quantum well

stage, and wherein the active region comprises a plurality of quantum well stages adjacent to each other each having electron quantum well layers surrounding a hole quantum well layer, the first semiconductor comprises InAs, and wherein there is an optical confinement layer adjacent to each barrier layer, the optical confinement layer comprising InP, and (b) means for providing optical feedback to provide lasing action in the active region, the means for providing optical feedback forming an edge-emitting laser or a vertical cavity surface-emitting laser.

With regard to any of the above listed claims (1,2,5,8, 11-14, 54, and 66, 39,40,41,43-46,48-51, 63-65, and 67) the only difference between said claims and the device disclosed by Peter et al. is that Peter et al. does not disclose that the first semiconductor comprising InAs is a semiconductor containing nitrogen, in fact comprising InAsN, or that the active region generates light having a wavelength greater than approximately 2 microns or approximately 3 microns. In her paper filed 12/19/05, Applicant admits that these are the only differences.

However, Major et al. discloses a semiconductor laser with an electron quantum well layer comprising InAsN. Note figures 3-7 and column 11 lines 3-18 of Major et al. Major et al. teaches that adding as little as 4% nitrogen to In_{.75}Ga_{.25}As (lattice matched to InP) while making minor adjustments to the In/Ga ratio to retain lattice match, produces a layer, with a band gap of .53 ev or less, which lases at 2-3 microns, making it useful for

LIDAR systems. Furthermore, according to Major et al., strain on such a layer is reduced by the introduction of nitrogen, further reducing the effective laser wavelength. Therefore, it would have been obvious to a person having skill in the art to replace the InAs of the first semiconductor of Peter et al.'s semiconductor laser with the InAsN such as taught by Major et al. in order to reduce band gap and strain, increasing effective laser wavelength to thus provide a laser capable of lasing at 2-3 microns, effective for LIDAR applications.

With regard to claims 16,18,20,21,24,25,26, and 59 Peter et al. disclose a multilayer semiconductor structure including an InP substrate and an active region, the active region comprising at least a hole quantum well layer of GaAsSb or InGaAsSb and an electron quantum well layer comprising InAs or InGaAs on each side of the hole quantum well layer to provide a type II quantum well structure, wherein the electron quantum well layer comprises a InAs layer, the thickness of each electron quantum well layer and hole quantum well layer is between approximately 10 and 50 angstroms, the electron quantum well layers and hole quantum well layer form a first quantum well stage, and wherein the active region comprises a plurality of quantum well stages adjacent to each other, and including means for providing optical feedback to form an edge-emitting laser or a vertical cavity surface-emitting laser.

With regard to claims 27,28,29,32, and 34-38 Peter et al. disclose a multilayer semiconductor structure including an InP substrate and an active region, the active region comprising at least a hole quantum well layer of GaAsSb and an electron quantum well layer comprising InAs on each side of the hole quantum well layer to provide a type II quantum well structure wherein (at least one of) the electron quantum well layers is lattice matched to InP, the thickness of each electron quantum well layer and hole quantum well layer is between approximately 10 and 50 angstroms, the electron quantum well layers and hole quantum well layer form a first quantum well stage, and wherein the active region comprises a plurality of quantum well stages adjacent to each other, and including means for providing optical feedback to form an edge-emitting laser or a vertical cavity surface-emitting laser.

With regard to any of the above listed claims (16,18,20,21,24,25,26, and 59, 27,28,29,32, and 34-38) the only difference between said claims and the device disclosed by Peter et al. is that Peter et al. does not disclose that the electron quantum well layer comprising InAs further comprises nitrogen so that it comprises InAsN. In her paper filed 12/19/05, Applicant admits that this is the only difference.

However, Major et al. discloses a semiconductor laser with an electron quantum well layer comprising InAsN. Note figures 3-7 and column 11 lines 3-18 of Major et al. Major et al. teaches that adding as little as 4% nitrogen to In_{.75}Ga_{.25}As (which is the InGaAs

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alloy, comprising InAs, that is lattice matched to InP) while making minor adjustments to the In/Ga ratio to retain lattice match, produces a layer with a band gap of .53 ev or less, which lases at 2-3 microns, making it useful for LIDAR systems. Furthermore, according to Major et al., strain on such a layer is reduced by the introduction of

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nitrogen, further reducing the effective laser wavelength. Therefore, it would have been obvious to a person having skill in the art to replace the InAs of the first semiconductor of Peter et al.'s semiconductor laser with the InAsN such as taught by Major et al. in

order to reduce band gap and strain, increasing effective laser wavelength to thus

provide a laser capable of lasing at 2-3 microns, effective for LIDAR application.

B. Claims 1,3-10, 55, and 56 stand rejected under 35 U.S.C. 103(a) as being unpatentable over DAPKUS (6,621,842) in view of PETER ET AL. ("Light-emitting diodes and laser diodes based on a Ga_{1-x}In_xAs/GaAs_{1-y}Sb_y" Applied Physics Letters, 04/05/99, Vol. 74 Issue 14, pp1951-1953).

With regard to claims 1,3-7, 55, and 56 Dapkus discloses an optoelectronic device comprising a multilayer semiconductor structure including an substrate and an active region, the active region comprising at least a hole quantum well layer of a semiconductor containing antimony and at least one electron quantum well layer adjacent to the hole quantum well layer which comprises a semiconductor containing nitrogen to provide a type II quantum well structure, wherein the semiconductor

containing antimony is GaAsSb or InGaAsSb, there is an electron quantum well layer on each side of the hole quantum well layer and there is a GaInP barrier layer adjacent to each electron quantum well layer on each side of the hole quantum well layer to provide a conduction band profile for the active region having a W-shaped configuration. Note figures 2-4, column 5 lines 1-67, column 6 lines 1-67, and column 7 lines 1-29 of Dapkus.

Dapkus does not disclose that the substrate is an InP substrate. However, Peter et al. discloses an optoelectronic device with an InP substrate. Note the first column of page 1951 of Peter et al. Peter et al. explain that the binary InP substrate is advantageous in that it is commercially used and thus technically advanced, has good thermal conductivity and low electrical resistance. Therefore, it would have been obvious to a person having skill in the art to replace the substrate of the device of Dapkus with the InP substrate such as taught by Peter et al. in order to provide a substrate that is technically advanced, has good thermal conductivity and low electrical resistance to thus provide higher reliability.

With regard to claims 1,8,9, and 10 Dapkus discloses an optoelectronic device comprising a multilayer semiconductor structure including an substrate and an active region, the active region comprising at least a hole quantum well layer of a semiconductor containing antimony and at least one electron quantum well layer

adjacent to the hole quantum well layer which comprises a semiconductor containing nitrogen to provide a type II quantum well structure, wherein the electron quantum well layers and hole quantum well layer form a first quantum well stage, and wherein the active region comprises a plurality of quantum well stages adjacent to each other each having electron quantum well layers surrounding a hole quantum well layer, and including a GalnP barrier layer between each quantum well stage to provide a conduction band profile having a W-shaped configuration. Note figures 2-4, column 5 lines 1-67, column 6 lines 1-67, and column 7 lines 1-29 of Dapkus.

Dapkus does not disclose that the substrate is an InP substrate. However, Peter et al. discloses an optoelectronic device with an InP substrate. Note the first column of page 1951 of Peter et al. Peter et al. explain that the binary InP substrate is advantageous in that it is commercially used and thus technically advanced, has good thermal conductivity and low electrical resistance. Therefore, it would have been obvious to a person having skill in the art to replace the substrate of the device of Dapkus with the InP substrate such as taught by Peter et al. in order to provide a substrate that is technically advanced, has good thermal conductivity and low electrical resistance to thus provide higher reliability.

Allowable Subject Matter

4. Claims 22,27,30,31,33,47,53,54 and 57-63 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Response to Arguments

5. Applicant's arguments with respect to claims 1,2,8,11-16,18,21,24,25,26,27,28, 29,32, 34-41,43-46,48-51,54,59, and 63-67 have been considered but are moot in view of the new ground(s) of rejection.

On pages 11-12 of the remarks, Applicants continue to insist that the instant invention, if not simply too complex for a person of ordinary skill in the art (PHOSITA) to comprehend, is at least so complex that PHOSITA would be frightened away by its complexity. Specifically Applicants state:

Each of the rejected claims recites an optoelectronic device that includes a hole quantum well layer containing antimony and an electron quantum well layer containing nitrogen built on an InP substrate. As noted by the Examiner, antimony-containing hole quantum well layers, nitrogen-containing electron quantum well layers and InP substrates are each individually known in the art. However, in light of the unpredictable nature of semiconductor based optoelectronic devices, the prior art does not provide motivation to select these individual components from different prior art devices and combine them into a single, functioning, optoelectronic device. As one of ordinary skill in the art would recognize, the building of a functional semiconductor-based optoelectronic device is no simple feat. Although the chemical and physical properties of each individual material in the device might be well characterized, the properties and behavior of the materials combined in a semiconductor stack is not easily predicted. Just a few of the many properties of the materials that have an effect on their ability to provide a functioning optoelectronic device (and the emission properties of any resulting device) include lattice mismatch and lattice strain, conduction band offsets, refractive index contrasts and relative thermal and electrical conductivities. Based on the complicated interplay between these and other material

properties, it would be unreasonable to assume that one could just mix and match the semiconductor layers from different devices and come up with a functioning optoelectronic device. Thus, at best, the prior art cited by the Examiner invites the reader to try each of numerous possible substrates, hole quantum well layers and electron quantum well layers until he possibly produces an operational optoelectronic device. However, any rejection of the claims based on such a general invitation would involve the application of an improper "obvious to try" rationale. (MPEP 2145)

It is Applicants' position that PHOSITA, although motivated to try to achieve the claimed invention, would not have been assured of achieving success, because PHOSITA would have been unable to perform the "calculations necessary to simulate the claimed devices in order to determine which systems would provide an operational optoelectronic device." Specifically applicants state:

In the present application, the inventors have done much more than simply mix and match semiconductor layers from different optoelectronic devices in the blind hope of producing a functioning optoelectronic device. As described in paragraphs 0028 and 0029 and illustrated in FIGS. 1-4 of the specification, the inventors performed the calculations necessary to simulate the claimed devices in order to determine which systems would provide an operational optoelectronic device. These calculations were needed to assess the properties of the systems based on the energy bandgap dependence on material composition, strain induced bandgap shifts, quantum confined states, carrier densities and optical response functions, among other factors. This information was used to determine what material compositions and thicknesses were needed for a given substrate. As one of ordinary skill in the art would recognize, such calculations and simulations are far from routine or trivial.

Paragraphs 0028 and 0029 and illustrated in FIGS. 1-4 of the instant specification read as follows:

[0027] In accordance with the invention, rather than employing type-I InGaAsN quantum wells (QWs) with high N-content, longer wavelengths may be accessed more readily via type-II InAsN/GaAsSb or InGaAsN/GaAsSb structures. The energy gap in a type-II structure is governed primarily by the relative conduction and valence band alignments in the two adjacent layers rather than by the bulk gap in a single layer. The resulting flexibility comes at the expense of reduced overlap between the electron and hole wave functions that now peak in different layers. In the midwave-infrared (3-5 ...mu.m) spectral range, the so-called "W" structure is utilized, in which two electron QWs sandwich a single hole QW to maximize the type-II wave function overlap and hence the differential gain. The electron QWs are in turn bounded by barrier layers that confine both carrier types. See J. R. Meyer, C. A. Hoffman, F. J. Bartoli, and L. R. Ram-Mohan, "Type II-quantum well lasers for the mid-wavelength infrared," Appl. Phys. Lett., 67 (6), 1995, pp. 757-759. To achieve mid-IR (2-5 .mu.m) operation from such a "W" structure, in the present invention a novel dilute-nitride type-II QW design is implemented

utilizing an InP substrate. A preferred but not limiting range of nitrogen content for the electron quantum wells is 10% or less.

[0028] For purposes of illustrating the invention, the band diagram for one period, or stage, of an example of an optoelectronic device with an approximate 0.30-eV energy gap (A=4.1 µm emission) at room temperature is shown at 10 in FIG. 1. This device is provided for example only, and it is understood that the invention is not limited to this example. Each of the two InAs_{0.97}N_{0.03} (2.6% compressive strain) electron QWs 12 are 12 angstroms thick, and the single GaAs_{0.35}Sb_{0.65} (1.2% compressive strain) hole QW 14 is 20 angstroms thick. Such a structure, in which two electron QWs surround a hole QW and two barrier layers 16 surround the electron QWs so as to maximize the wave function overlap, is referred to as a type II "W" configuration because of the shape of the conduction band profile. The advantages of the W configuration are discussed in J. R. Meyer, C. A. Hoffman, F. J. Bartoli, and L. R. Ram-Mohan, "Type II-quantum well lasers for the mid-wavelength infrared," Appl. Phys. Lett., 67 (6), 1995, pp. 757-759. See, also U.S. Pat. No. 5,793,787. In FIG. 1, the InAsN electron QWs 12 are surrounded by In.sub.0.75Ga.sub.0.25P (1.8% tensile strained) barriers 16 (130 angstroms thick), which provide strain compensation. Since adequate hole confinement often becomes an issue when type-I GaAsN and InGaAsN active regions are employed, the strong confinement of both carrier types here represents an additional advantage of the type-II approach. The curves 17 and 18 in FIG. 1 illustrate the spatial profiles of the ground-state electron and hole wave functions, respectively. Energy dispersion relations, wave functions, and optical matrix elements were calculated for the device of FIG. 1 using a 10-band k dot p formalism. The band anti-crossing (BAC) model was employed to incorporate a spin-degenerate nitrogen-like band that accounts for the interaction of F-like and N-like states in the dilute-nitride layers. Band parameters for the non-nitride and dilute-nitride materials are taken from I. Vurgaftman and J. R. Meyer, "Band parameters for nitrogen-containing semiconductors," J. Appl. Phys. 94, 3675 (2003).

The only "calculations and simulations" applicants disclose in these paragraphs is that the "band anti-crossing (BAC) model was employed [using] band parameters [from] Vurgaftman and Meyer, ... (2003)."

The band anti-crossing (BAC) calculational model was developed in the late 20th century by a group of scientists working at the Materials Sciences Division, Lawrence Berkeley National Laboratory, as is evident from, for example, Shan et al., "Band Anticrossing in GalnNAs Alloys," Phys. Rev. Lett. Vol. 82, No. 6, pp 1221-1224 (1999), and "Striking Effects Of Nitrogen In Semiconductor Alloy Explained," Press Release, Lawrence Berkeley National Laboratory, June 9, 1999.

Applicants knew the use of the Lawrence Berkeley group's band anti-crossing (BAC) model would have been crucial to one's ability to make the claimed invention because Applicants in fact found the BAC model to be crucial. Insofar as the use of this model is crucial to one's ability to make the claimed invention, and Applicants knew the Lawrence Berkeley group disclosure of the band anti-crossing (BAC) model was 102(b) prior art to Applicants' present application, the Examiner feels Applicants' better course of action would have been to disclose the prior art Lawrence Berkeley disclosure rather than force the Examiner to dig it up.

The band anti-crossing (BAC) calculational model was available to PHOSITA as prior art. Band parameters for the non-nitride and dilute-nitride materials were available to PHOSITA as prior art in Vurgaftman and J. R. Meyer, "Band parameters for nitrogen-containing semiconductors," J. Appl. Phys. 94, 3675 (2003). Applicant's argument that as "one of ordinary skill in the art would recognize, such calculations and simulations are far from routine or trivial," thus boils down to an argument that PHOSITA would have been too dad-blamed lazy to have displayed the gumption Applicants employed to crank through the complexities of the Berkeley group's BAC model (using the specific data supplied by Vurgaftman et al.) to arrive at the claimed invention.

The examiner is familiar with most recent STM (suggestion-teaching-motivation) jurisprudence (from, say *Dembiczak*, 50 USPQ2d 1614 (1999), through *Kahn*, 78

USPQ2d 1329 (2006)) The examiner was unaware that the STM test required a factual finding of "gumption." Would Applicant please be so kind as to point out the relevant cases that made "gumption" part of the STM test?

On page 13 Applicants argue, "Applicants respectfully submit that claims 27, 54, 59 and 63 clearly recite an electron quantum well layer of InAsN and not an electron quantum well layer of InGaAsN." It remains the Examiner's (unproven) belief that a "well" of "pure" ternary InAsN, formed over InP, would have to have a lattice constant close to that of InP, or else be full of cracks, voids, discontinuities and "slip" in general. Producing such a lattice constant would require adjusting the N content (there being nothing in a ternary compound to adjust but the relative content of In and N) to the point where the band gap of said compound would go negative (metallic).

However, Applicants have made it clear that absolutely no gallium is allowed in the wells of claims 27, 54, 59 and 63. On this understanding, there being no "smoking gun" of non-enablement, claims 27, 54, 59 and 63 are allowable.

Conclusion

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thomas L. Dickey whose telephone number is 571-272-1913. The examiner can normally be reached on Monday-Thursday 8-6.

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan J. Flynn can be reached on 571-272-1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Thomas L. Dickey Patent Examiner Art Unit 2826

02/06